

SN54AHCT16541, SN74AHCT16541 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCLS339A – MARCH 1996 – REVISED NOVEMBER 1996

- **Members of the Texas Instruments Widebus™ Family**
- **Inputs Are TTL-Voltage Compatible**
- **EPIC™ (Enhanced-Performance Implanted CMOS) Process**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

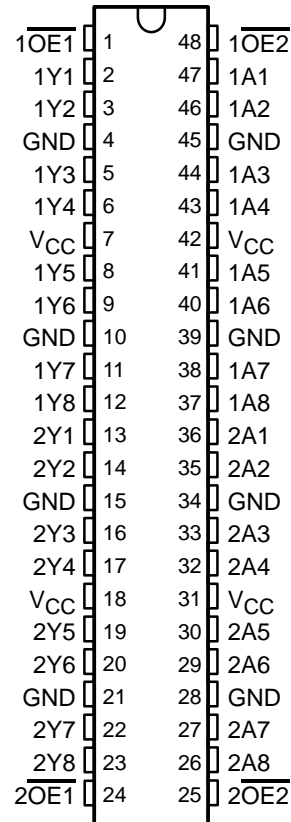
description

The 'AHCT16541 are noninverting 16-bit buffers composed of two 8-bit sections with separate output-enable signals. For either 8-bit buffer section, the two output-enable ($\overline{1OE1}$ and $\overline{1OE2}$ or $\overline{2OE1}$ and $\overline{2OE2}$) inputs must both be low for the corresponding Y outputs to be active. If either output-enable input is high, the outputs of that 8-bit buffer section are in the high-impedance state.

The SN74AHCT16541 is available in TI's shrink small-outline (DL) and thin shrink small-outline (DGG) packages, which provide twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN54AHCT16541 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74AHCT16541 is characterized for operation from –40°C to 85°C.

SN54AHCT16541 . . . WD PACKAGE
SN74AHCT16541 . . . DGG OR DL PACKAGE
(TOP VIEW)



FUNCTION TABLE
(each 8-bit section)

INPUTS			OUTPUT Y
$\overline{OE1}$	$\overline{OE2}$	A	
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z



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**TEXAS
INSTRUMENTS**

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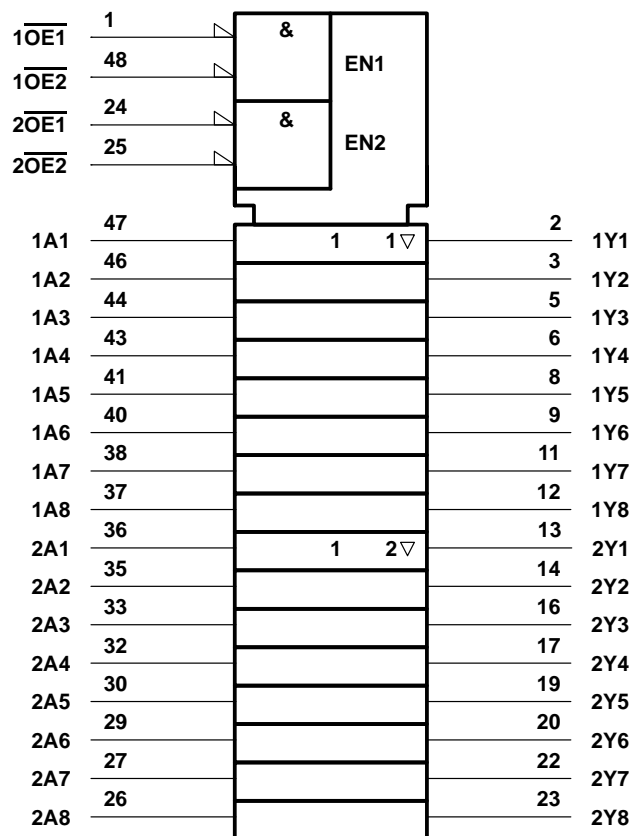
SN54AHCT16541, SN74AHCT16541

16-BIT BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

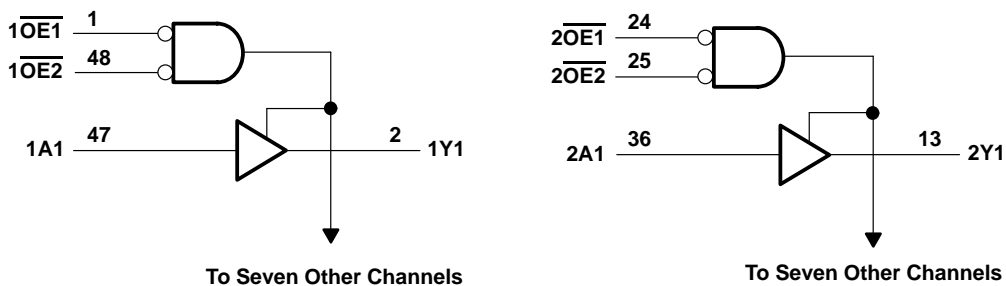
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



PRODUCT PREVIEW



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SN54AHCT16541, SN74AHCT16541 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCLS339A – MARCH 1996 – REVISED NOVEMBER 1996

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Output voltage range, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	–20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	–20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through each V_{CC} or GND	±75 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2): DGG package	0.85 W
DL package	1.2 W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

	SN54AHCT16541		SN74AHCT16541		UNIT
	MIN	MAX	MIN	MAX	
V_{CC} Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH} High-level input voltage	2		2		V
V_{IL} Low-level input voltage		0.8		0.8	V
V_I Input voltage	0	5.5	0	5.5	V
V_O Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH} High-level output current		–8		–8	mA
I_{OL} Low-level output current		8		8	mA
$\Delta t/\Delta v$ Input transition rise or fall rate		20		20	ns/V
T_A Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

PRODUCT PREVIEW



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AHCT16541		SN74AHCT16541		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 μA	4.5 V	4.4	4.5		4.4		4.4		V
	I _{OH} = -8 mA		3.94			3.8		3.8		
V _{OL}	I _{OL} = 50 μA	4.5 V			0.1		0.1		0.1	V
	I _{OL} = 8 mA				0.36		0.44		0.44	
I _{OZ}	V _O = V _{CC} or GND	5.5 V			±0.25		±2.5		±2.5	μA
I _I	V _I = V _{CC} or GND	5.5 V			±0.1		±1		±1	μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			4		40		40	μA
ΔI _{CC} [†]	One input at 3.4 V, Other inputs at GND or V _{CC}	5.5 V			1.35		1.5		1.5	μA
C _i	V _I = V _{CC} or GND	5 V		2	10				10	pF
C _o	V _O = V _{CC} or GND	5 V		4						pF

[†] This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			SN54AHCT16541		SN74AHCT16541		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH} *	A	Y	C _L = 15 pF		4.1	6	1	6.5	1	6.5	ns
t _{PHL} *					3.7	5.5	1	6.5	1	6.5	
t _{PZH} *	\overline{OE}	Y	C _L = 15 pF		5	7	1	8	1	8	ns
t _{PZL} *					5	7	1	8	1	8	
t _{PHZ} *	\overline{OE}	Y	C _L = 15 pF		4.5	7	1	8	1	8	ns
t _{PLZ} *					4.5	7	1	8	1	8	
t _{PLH}	A	Y	C _L = 50 pF		6.2	8.5	1	9.5	1	9.5	ns
t _{PHL}					6	8.5	1	9.5	1	9.5	
t _{PZH}	\overline{OE}	Y	C _L = 50 pF		7.5	10	1	12	1	12	ns
t _{PZL}					7.5	10	1	12	1	12	
t _{PHZ}	\overline{OE}	Y	C _L = 50 pF		7	10	1	12	1	12	ns
t _{PLZ}					7	10	1	12	1	12	

* On products compliant to MIL-PRF-38535, this parameter is ensured but not production tested.

output-skew characteristics, C_L = 50 pF (see Note 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	SN74AHCT16541				UNIT
				T _A = 25°C		MIN	MAX	
				MIN	MAX			
t _{sk(o)}	A	Y	5 V ± 0.5 V	1		1		ns

NOTE 4: Characteristics are determined during product characterization and ensured by design.

noise characteristics, $V_{CC} = 5\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$ (see Note 5)

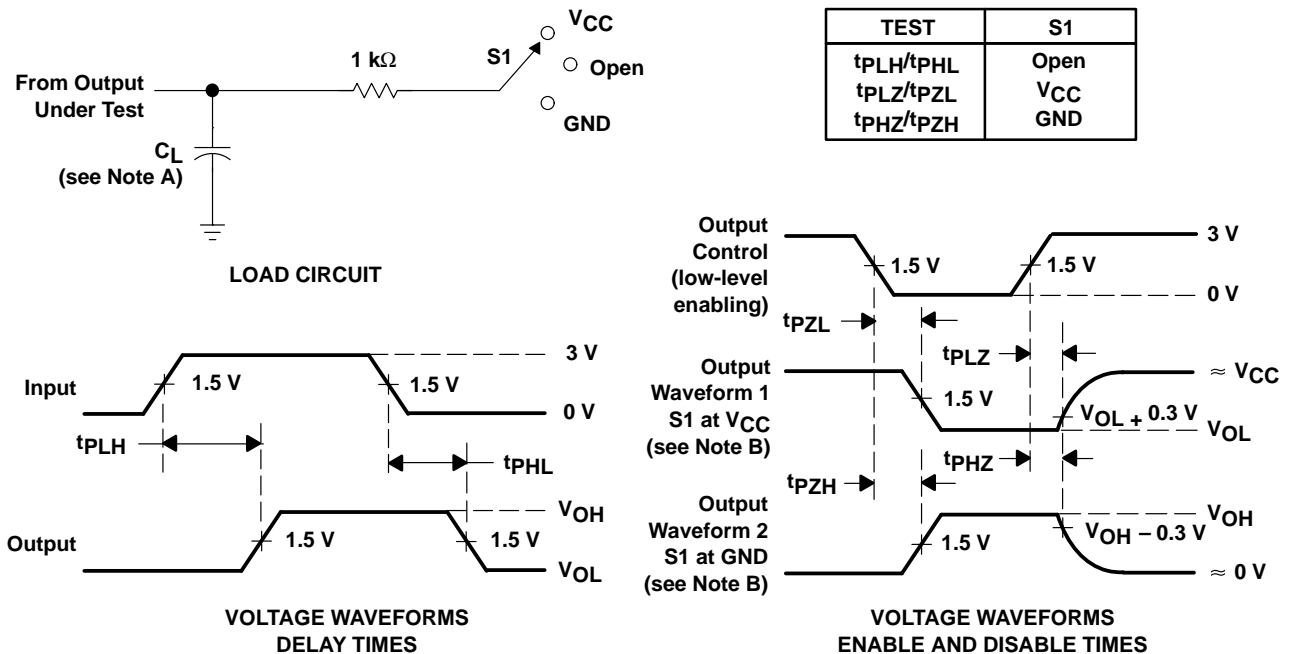
PARAMETER	SN74AHCT16541		UNIT
	MIN	MAX	
$V_{OL(P)}$ Quiet output, maximum dynamic V_{OL}		0.8	V
$V_{OL(V)}$ Quiet output, minimum dynamic V_{OL}		−0.8	V
$V_{OH(V)}$ Quiet output, minimum dynamic V_{OH}	4.6		V
$V_{IH(D)}$ High-level dynamic input voltage	2		V
$V_{IL(D)}$ Low-level dynamic input voltage		0.8	V

NOTE 5: Characteristics are determined during product characterization and ensured by design for surface-mount packages only.

operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load, $f = 1\text{ MHz}$	12	pF

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r = 3\text{ ns}$, $t_f = 3\text{ ns}$.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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